

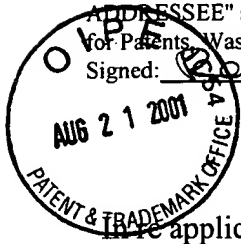
"EXPRESS MAIL" MAILING LABEL NUMBER EL 527 873 252 US

DATE OF DEPOSIT August 21, 2001

I hereby certify that this paper or fee is being deposited with the United States Postal Service "EXPRESS MAIL POST OFFICE TO ADDRESSEE" service under 37 CFR 1.10 on the date indicated above and addressed to: Box CPA FEE, Assistant Commissioner for Patents, Washington, DC 20231

Signed: Raquel Graeber

Raquel Graeber



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Re application of:

Yao, et al.

Serial No. 09/457,929

Filed: December 8, 1999

For: WAFER CARRIER AND
SEMICONDUCTOR APPARATUS
FOR PROCESSING A
SEMICONDUCTOR SUBSTRATE

Examiner: Jeffrie R. Lund

Group Art Unit: 1763

San Francisco, CA 94111

Date: August 21, 2001

#110
8/28/01
MW

RECEIVED
AUG 28 2001
TC 1700

PRELIMINARY AMENDMENT

Assistant Commissioner for Patents
Washington, D.C. 20231

Sir:

The following is a preliminary amendment in the subject continuation application and is in response to a Final Office Action mailed May 21, 2001. Please amend the referenced application as follows:

IN THE SPECIFICATION

Please replace the paragraph beginning at page 7, line 3, with the following rewritten paragraph:

--To maintain the desirable line or point contact with the peripheral edge of the wafer and to provide secure support of the wafer, the thermal expansion of the wafer carrier is considered. Preferably, little thermal expansion occurs during the process so that the desired angle of the incline is preserved. Specifically, the wafer carrier is comprised of a material having an isotropic coefficient of thermal expansion in the range of $2.6 \times 10^{-6}/^{\circ}\text{C}$ to $5 \times 10^{-6}/^{\circ}\text{C}$, with the lower values preferred. Materials with suitable coefficients of thermal expansion include silicon and silicon carbide.--